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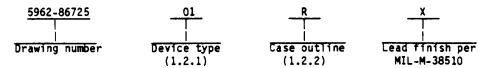
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<u>DISTRIBUTION STATEMENT A.</u> Approved for public release; distribution is unlimited. **DESC FORM 193**MAY 86

1. SCOPE

1.1 <u>Scope</u> This drawing describes device requirements for class B microcircuits in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices."

1.2 Part number. The complete part number shall be as shown in the following example:



1.2.1 Device types. The device type shall identify the circuit function as follows:

Device type Generic number Circuit function

O1 AM25S241 Non-inverting octal buffer with three-state outputs

1.2.2 <u>Case outlines</u>. The case outlines shall be as designated in appendix C of MIL-M-38510, and as follows:

Outline letter

## Case outline

R

D-8 (20-lead, 1/4" X 1-1/16"), dual-in-line package

ς

F-9 (20-lead, 1/4" X 1/2"), flat package

1.3 Absolute maximum ratings.

Supply voltage range- - - - - - - - - - - --0.5 V dc to +7.0 V dc Input voltage range - - - - - - - - - --1.5 V to +7.0 V -65°C to +150°C 2.2 W +300 C Lead temperature (soldering, 10 seconds) - - -Thermal resistance, junction-to-case( $\theta_{JC}$ ): 25°C/W 20°C/W Case R- - - - - - - - - - - - - - - -Case S------Junction temperature (T<sub>J</sub>) - - - - - - -+150°C -30 mA to +5.0 mA DC output current into outputs- - - - - -+30 mA

1.4 Recommended operation conditions.

 $\overline{I/Must}$  withstand the added PD due to short circuit test (e.g.,  $I_{OS}$ ).

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2.1 Government specification and standard. Unless otherwise specified, the following specification and standard, of the issue listed in that issue of the Department of Defense Index of Specifications and Standards specified in the solicitation, form a part of this drawing to the extent specified herein.

**SPECIFICATION** 

**MILITARY** 

MIL-M-38510

- Microcircuits, General Specification for.

STANDARD

**MILITARY** 

MIL-STD-883

- Test Methods and Procedures for Microelectronics.

(Copies of the specification and standard required by manufacturers in connection with specific acquisition functions should be obtained from the contracting activity or as directed by the contracting activity.)

- 2.2 Order of precedence. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing shall take precedence.
  - 3. REQUIREMENTS
- 3.1 Item requirements. The individual item requirements shall be in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices" and as specified herein.
- 3.2 <u>Design, construction, and physical dimensions</u>. The design, construction, and physical dimensions shall be as specified in MIL-M-38510 and herein.
  - 3.2.1 Terminal connections. The terminal connections shall be as specified on figure 1.
  - 3.2.2 Truth table. The truth table shall be as specified on figure 2.
  - 3.2.3 Logic diagram. The logic diagram shall be as specified on figure 3.
  - 3.2.4 Case outlines. The case outlines shall be in accordance with 1.2.2 herein.
- 3.3 Electrical performance characteristics. Unless otherwise specified, the electrical performance characteristics are as specified in table I and apply over the full recommended ambient operating temperature range.
- 3.4 Marking. Marking shall be in accordance with MIL-STD-883 (see 3.1 herein). The part shall be marked with the part number listed in 1.2 herein. In addition, the manufacturer's part number may also be marked as listed in 6.4 herein.

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Test	Symbol	Conc	! Group A		its	Unit	
	 	-55°C < 1   unless other 	TA < +125°C -wise specified	subgroups	Min	Max	
High level output voltage	VOH	V <sub>CC</sub> = +4.5 V   V <sub>IN</sub> = 0.8 V or   2.0 V	V <sub>B1</sub> = 0.8 V I <sub>OH</sub> = -3.0 mA	1, 2, 3	2.4		V
	 	 	V <sub>B1</sub> = 0.5 V   I <sub>OH</sub> = -12.0 mA	1, 2, 3	2.0	 	<b>V</b> 
Low level output voltage	VOL	V <sub>CC</sub> = +4.5 V   V <sub>IN</sub> = 0.8 V or 2.0 V   I <sub>OL</sub> = 48.0 mA		1, 2, 3		0.55	٧
Hysteresis (V <sub>T+</sub> - V <sub>T-</sub> )	VHYST	  Y <sub>CC</sub> = +4.5 V 		1, 2, 3	0.2	1	V
Input clamp voltage	V <sub>IC</sub>	  V <sub>CC</sub> = +4.5 V  I <sub>IN</sub> = -18 mA		1, 2, 3		-1.2	V
High level input current	IIH1	  V <sub>CC</sub> = +5.5 V  V <sub>IN</sub> = 2.7 V		1, 2, 3		50	μ <b>Α</b>
	II IH2	  V <sub>CC</sub> = +5.5 V  V <sub>IN</sub> = 5.5 V		1, 2, 3		1.0	i mA

Any A

Any G

1/

1, 2, 3

1, 2, 3

1, 2, 3

1, 2, 3

1, 2, 3 | -50

1-0.4

1-2.0

-225

50

- 50

mΑ

mΑ

mΑ

μА

μA

See footnotes at end of table.

Output short circuit IOS current

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Low level input current

Off-state output

current

VCC = 5.5 V VIN = 0.5 V

V<sub>CC</sub> = +5.5 V

V<sub>CC</sub> = +5.5 V V<sub>OUT</sub> = 2.4 V

V<sub>CC</sub> = +5.5 V V<sub>OUT</sub> = 0.5 V

IIL

IOZH

IOZL

	ı	
7		7

Test	Symbol	Condi	tions	Group A	Limi	ts	Unit
,		-55°C < TA   unless otherw	< +125°C	subgroups	Min	Max	   
Supply current	ICCH	  Y <sub>CC</sub> = +5.5 Y   	IG = 0.0 V   2G = 3.0 V   Data = 3.0 V	1, 2, 3		65	180
	ICCL	  - 	IG = 0.0 V 2G = 3.0 V Data = 0.0 V	1, 2, 3		105	m/
	Iccz		IG = 3.0 V   2G = 0.0 V   Data = 0.0 V	1, 2, 3		120	m4
Functional testing	   	  See 4.3.1c 		   7,8 	   		
Propagation delay from Ai to Yi	t <sub>PHL</sub>	  C <sub>L</sub> = 50 pF  R <sub>L</sub> 1 = 1 kΩ  R <sub>L</sub> 2 = 90Ω  See figure 4	T <sub>A</sub> = 25°C 2/	9		9	ns
			3/	9, 10, 11		12	ns
Propagation delay from output enable to Yi 4/	t <sub>PZH</sub>		T <sub>A</sub> = 25°C	   9 		12	l ns
			3/	9, 10, 11		13	l ns
Propagation delay rom output enable to Yi 4/	tpZL		T <sub>A</sub> = 25°C	9		15	ns
			<u>3</u> /	9, 10, 11		18	ns
ropagation delay rom output enable o Yi 4/	t <sub>PHZ</sub> ,		T <sub>A</sub> = 25°C	9		18	ns

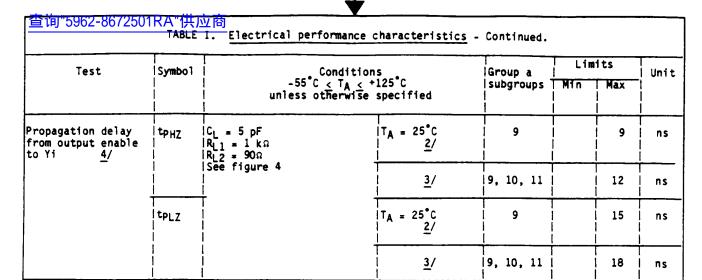
See footnotes at end of table.

MILITARY DRAWING
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A
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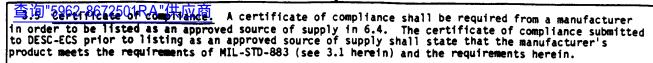
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<sup>1/</sup> Not more than one output shall be shorted at a time. Duration of the short circuit test should not exceed one second.

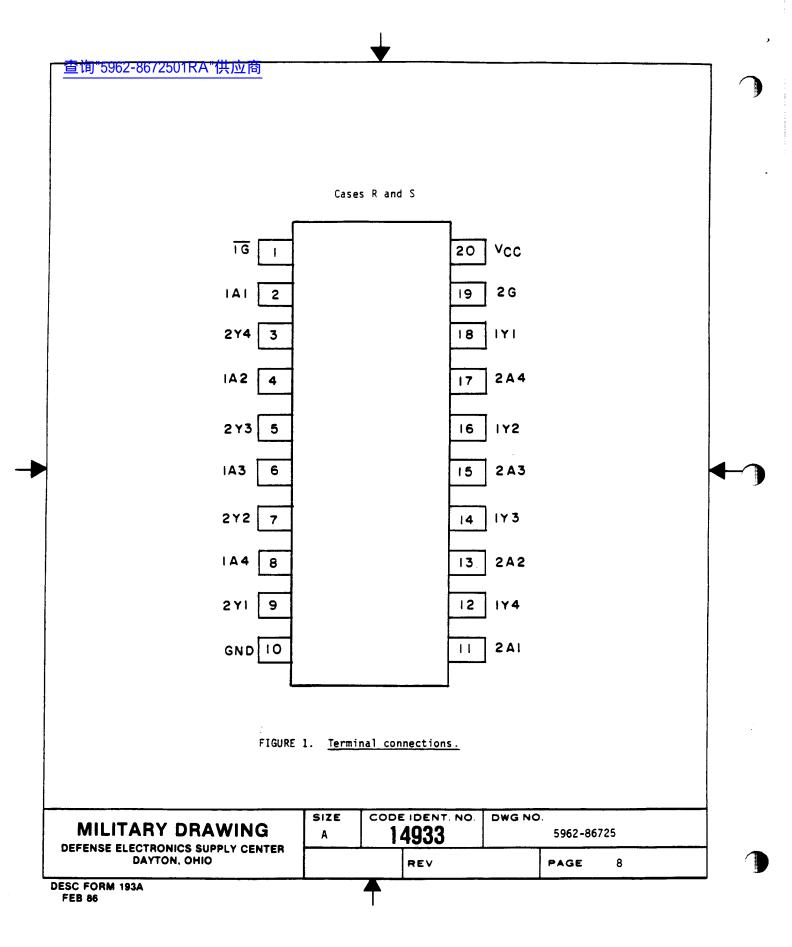
- 2/ V<sub>CC</sub> = 5.0 V.
- 3/ V<sub>CC</sub> = 4.5 V to 5.5 V.
- 4/ Add 3 ns for 2G Enable/Disable delays.

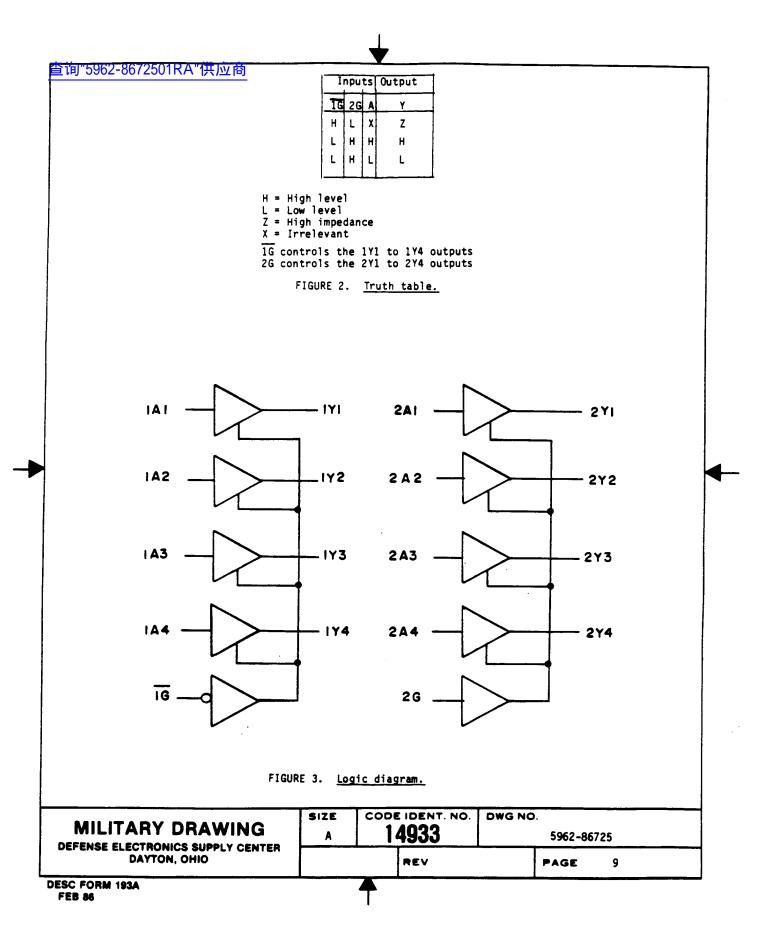
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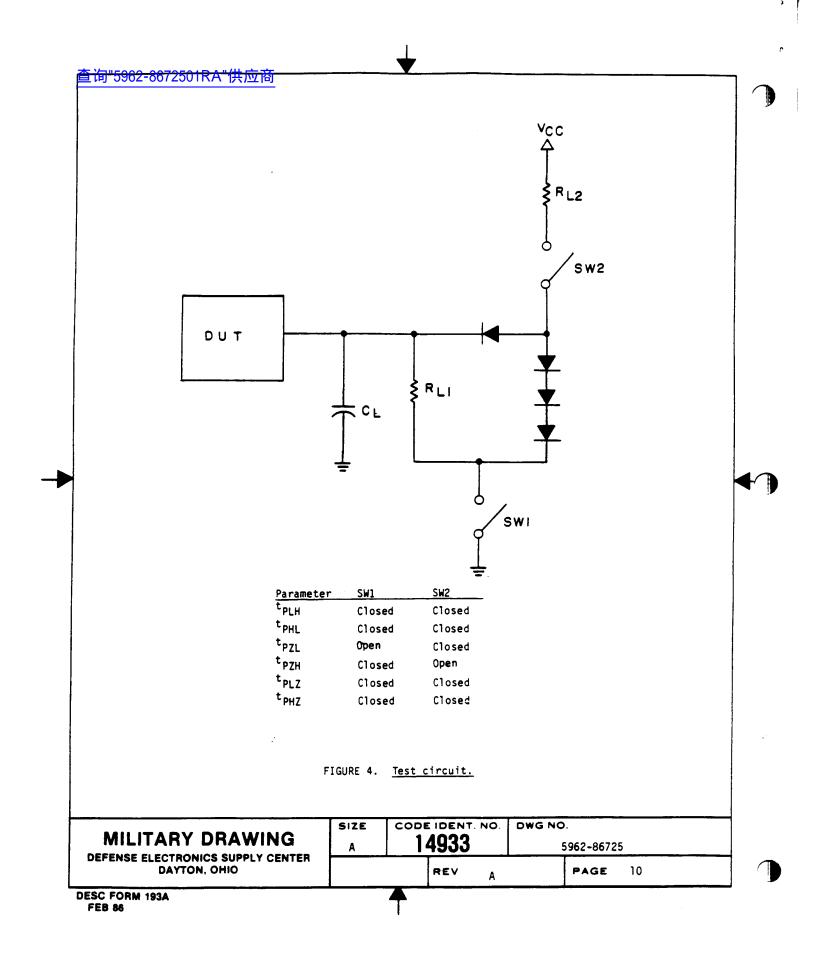


- 3.6 Certificate of conformance. A certificate of conformance as required in MIL-STD-883 (see 3.1 herein) shall be provided with each lot of microcircuits delivered to this drawing.
- 3.7 Notification of change. Notification of change to DESC-ECS shall be required in accordance with MIL-STD-883 (see 3.5 herein).
- 3.8 <u>Verification and review.</u> DESC, DESC's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.
  - 4. QUALITY ASSURANCE PROVISIONS
- 4.1 <u>Sampling and inspection.</u> Sampling and inspection procedures shall be in accordance with section 4 of MIL-M-38510 to the extent specified in MIL-STD-883 (see 3.1 herein).
- 4.2 <u>Screening.</u> Screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection. The following additional criteria shall apply:
  - a. Burn-in test (method 1015 of MIL-STD-883).
    - Test condition A, C, or D using the circuit submitted with the certificate of compliance (see 3.5 herein).
    - (2)  $T_A = +125$ °C, minimum.
  - b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.
- 4.3 Quality conformance inspection. Quality conformance inspection shall be in accordance with method 5005 of MIL-STD-883 including groups A, B, C, and D inspections. The following additional criteria shall apply.
  - 4.3.1 Group A inspection.
    - a. Tests shall be as specified in table II herein.
    - b. Subgroups 4, 5, and 6 in table I, method 5005 of MIL-STD-883 shall be omitted.
    - c. Subgroups 7 and 8 tests shall verify the truth table.
  - 4.3.2 Groups C and D inspections.
    - a. End-point electrical parameters shall be as specified in table II herein.
    - b. Steady-state life test (method 1005 of MIL-STD-883) conditions:
      - Test condition A, C, or D using the circuit submitted with the certificate of compliance (see 3.5 herein).
      - (2)  $T_A = +125$ °C, minimum.
      - (3) Test duration: 1,000 hours, except as permitted by appendix B of MIL-M-38510 and method 1005 of MIL-STD-883.

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## 查询"5962-8672501RA"供应商ABLE II. <u>Electrical test requireme</u>nts.

MIL-STD-883 test requirements	Subgroups (per method 5005, table I)
  Interim electrical parameters   (method 5004)	
  Final electrical test parameters   (method 5004)	1*, 2, 3, 7, 8, 9
  Group A test requirements   (method 5005)	1, 2, 3, 7, 8, 9, 10**, 11**
Groups C and D end-point electrical parameters (method 5005)	1, 2, 3

\* PDA applies to subgroup 1.

\*\* Subgroups 10 and 11, if not tested, shall be guaranteed to the limits specified in table I.

## 5. PACKAGING

- 5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-M-38510.
- 6. NOTES
- 6.1 Intended use. Microcircuits conforming to this drawing are intended for use when military specifications do not exist and qualified military devices that will perform the required function are not available for OEM application. When a military specification exists and the product covered by this drawing has been qualified for listing on QPL-38510, the device specified herein will be inactivated and will not be used for new design. The QPL-38510 product shall be the preferred item for all applications.
- 6.2 Replaceability. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.
- 6.3 Comments. Comments on this drawing should be directed to DESC-ECS, Dayton, Ohio 45444, or telephone 513-296-5375.

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will be added as they become available. The vendor listed herein has agreed to this drawing and a certificate of compliance (see 3.5 herein) has been submitted to DESC-ECS.

   Military drawing   part number	Vendor     CAGE     number	Vendor Similar part number 1/
5962-8672501RX	34335	AM25S241/BRA
5962-8672501SX	34335	AM25S241/BSA

1/ Caution. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.

Vendor CAGE number

34335

Vendor name and address

Advanced Micro Devices, Inc. 901 Thompson Place P.O. Box 3453 Sunnyvale, CA 94088

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